

TP 300-S

Soft, Conductive Gap Filler Pad

TP 300 is an extremely soft gap filler pad that also harnesses exceptional thermally conductive characteristics. TP 300 can meet the design needs of numerous design requirements and specifications. TP 300 will provide the innate thermal requirements your design needs without over stressing the components or cases.



Features and Benefits

- 3.0 W/m.K
- Ultra soft and highly compliant
- Naturally tacky, easing application
- High electrical insulation
- Good temperature resistance

Typical Applications

- Networking and Telecommunications
- IT: Notebooks, Tablets, Power Conversion
- Industrial: LEDs, Power Supplies and Conversion
- Automotive: Control Modules, Turbo Actuators
- Consumer Electronics: Gaming Systems, LCDs, and Graphic Cards

Typical Properties

Attribute	Value	Test Method
	TP 300-S	-
Composition	Ceramic Filler + Silicone	-
Color	Light Blue	Visual
Thickness (mm)	0.5 to 10.0	ASTM D374
Density (g/cc)	3.0	ASTM D792
Hardness (Shore OO)	55(Thickness≥1.0 Shore OO 40)	ASTM D2240
Usage Temperature (°C)	- 40 to 150	-
Electrical		
Breakdown Voltage (kV/mm)	> 5.0	ASTM D149
Volume Resistivity (Ω.cm)	10 ¹³	ASTM D257
Dielectric Constant @1MHz	7.3	ASTM D150
Flammability	V-0	UL 94
Thermal		
Thermal Conductivity (W/m.K)	3.0	ISO 22007-2

Storage

Store in a cool, dry, well-ventilated place.

Shelf life

Shelf life of the product is 12 months after date of shipment

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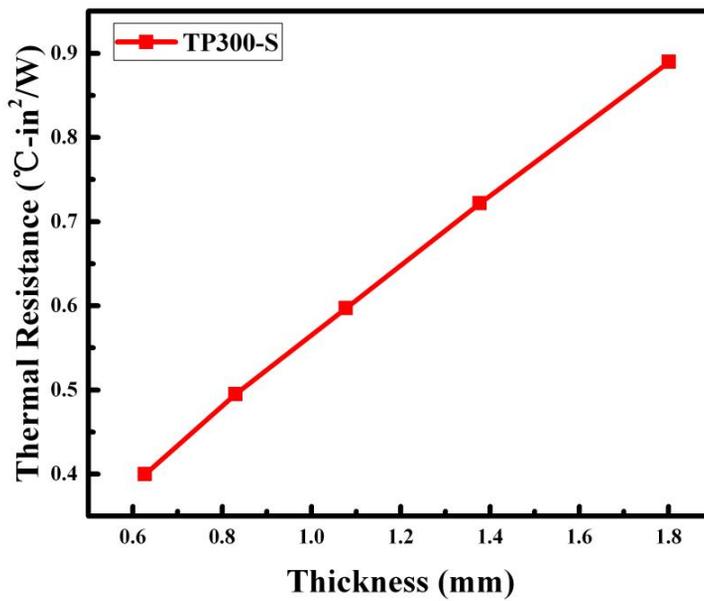


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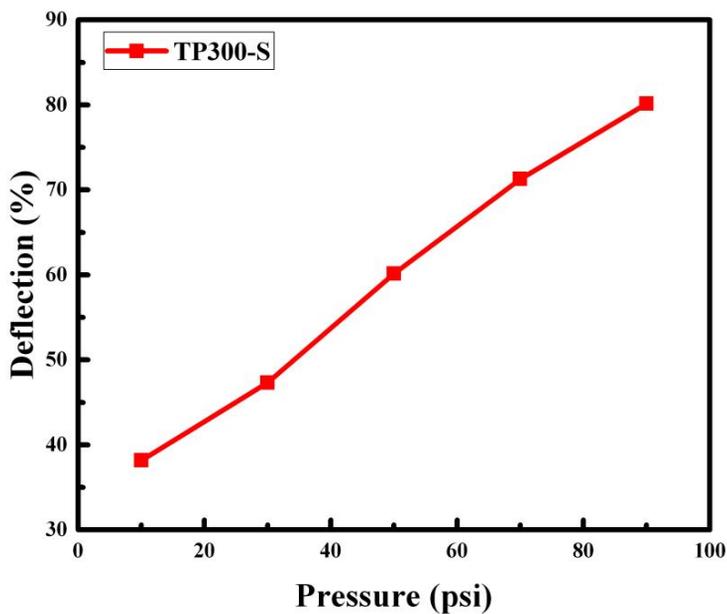
Thickness vs. Thermal Resistance

Reference only



Pressure vs. Deflection

Reference only



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